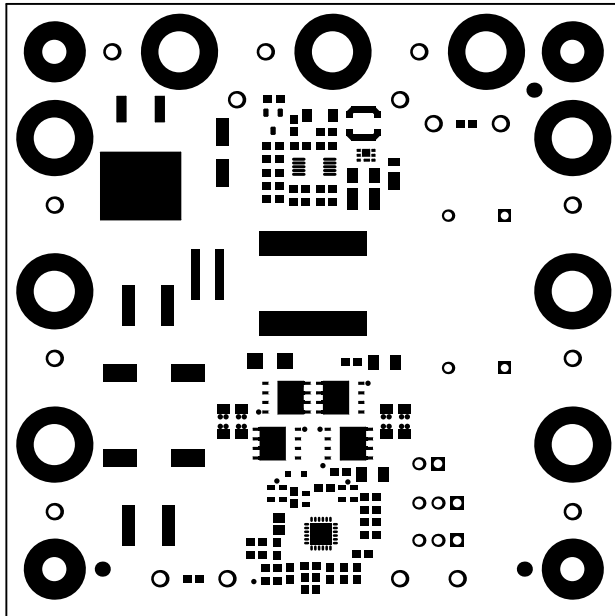
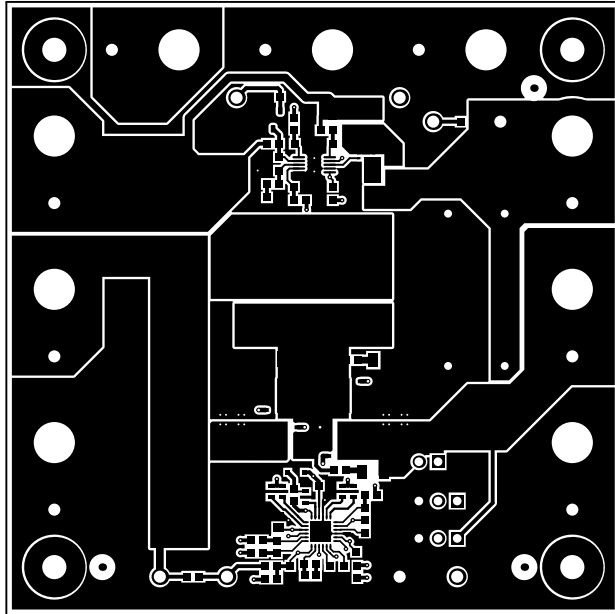


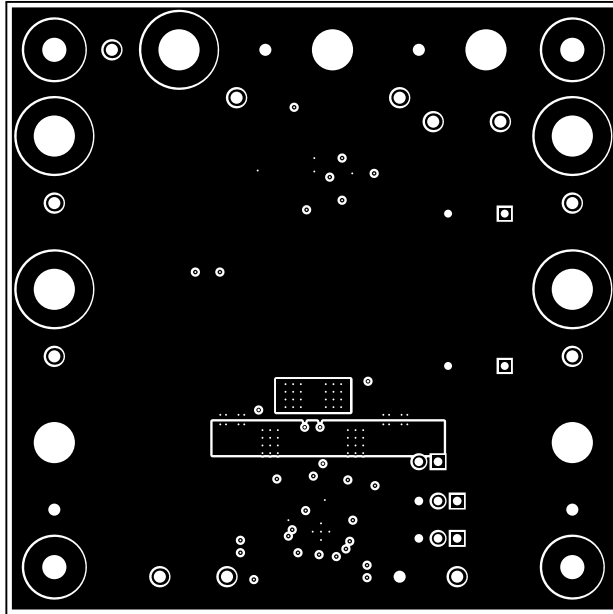
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20818		
PLOT NAME = Top Overlay	GENERATED : 3/29/2017	1:08:59 PM	TEXAS INSTRUMENTS



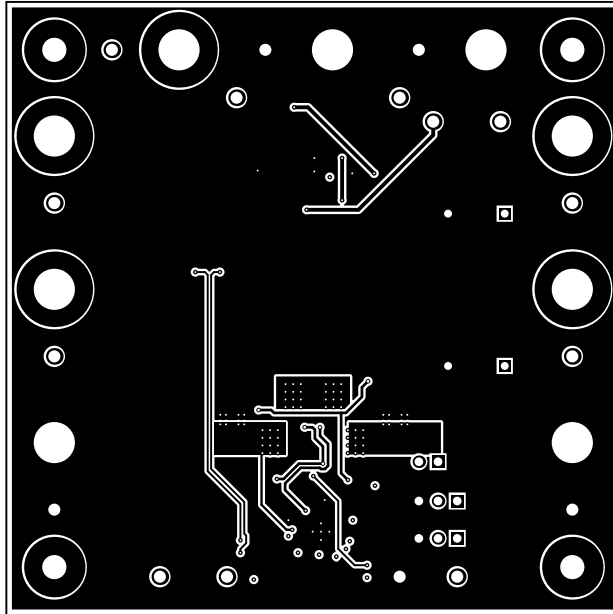
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20818		
PLOT NAME = Top Solder Mask	GENERATED : 3/29/2017 1:09:01 PM	TEXAS INSTRUMENTS	



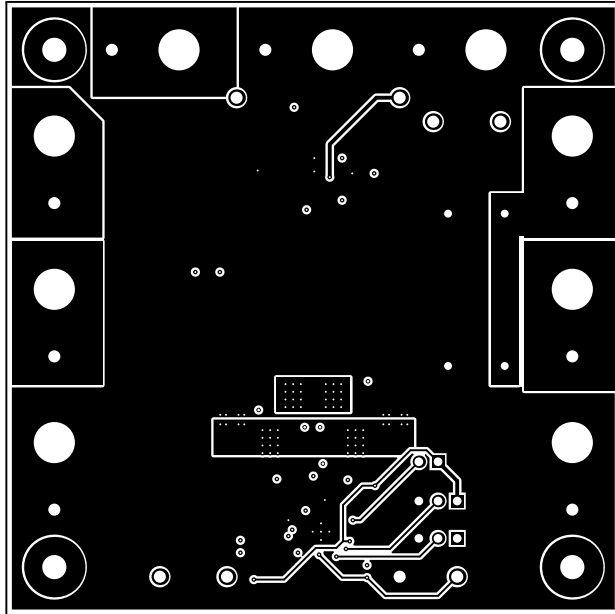
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20818		
PLOT NAME = Top Layer	GENERATED : 3/29/2017 1:09:02 PM	TEXAS INSTRUMENTS	



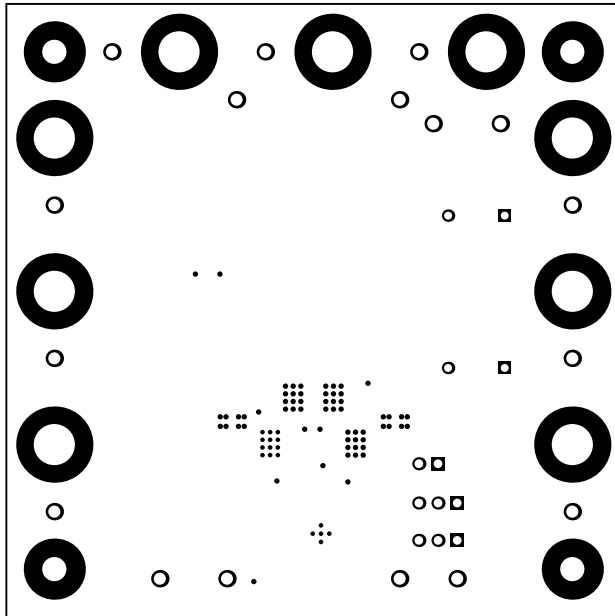
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: PMP20818		
PLOT NAME = Signal Layer 1	GENERATED : 3/29/2017 1:09:03 PM	TEXAS INSTRUMENTS	



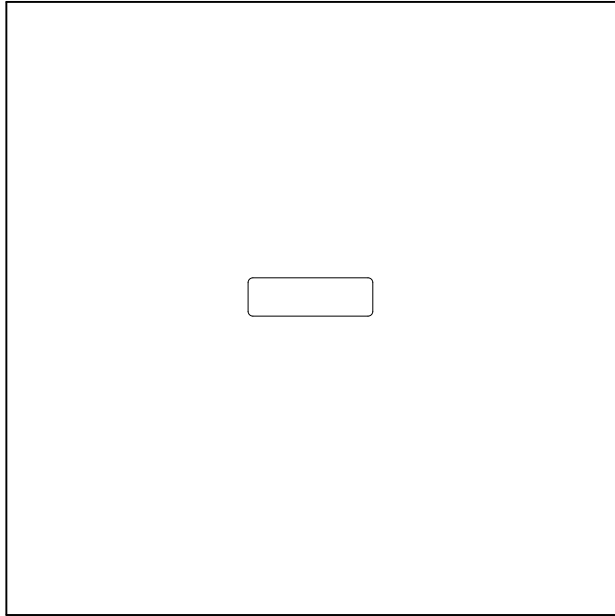
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: PMP20818		
PLOT NAME = Signal Layer 2	GENERATED : 3/29/2017 1:09:04 PM	TEXAS INSTRUMENTS	



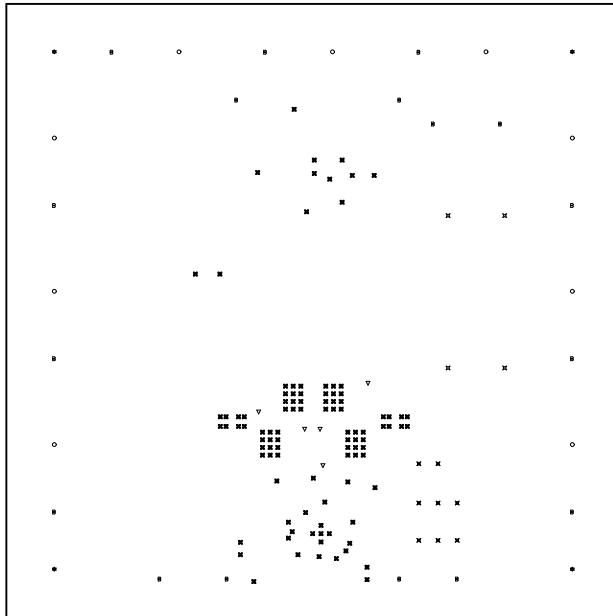
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20818		
PLOT NAME = Bottom Layer	GENERATED : 3/29/2017 1:09:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20818		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/29/2017 1:09:06 PM	TEXAS INSTRUMENTS	

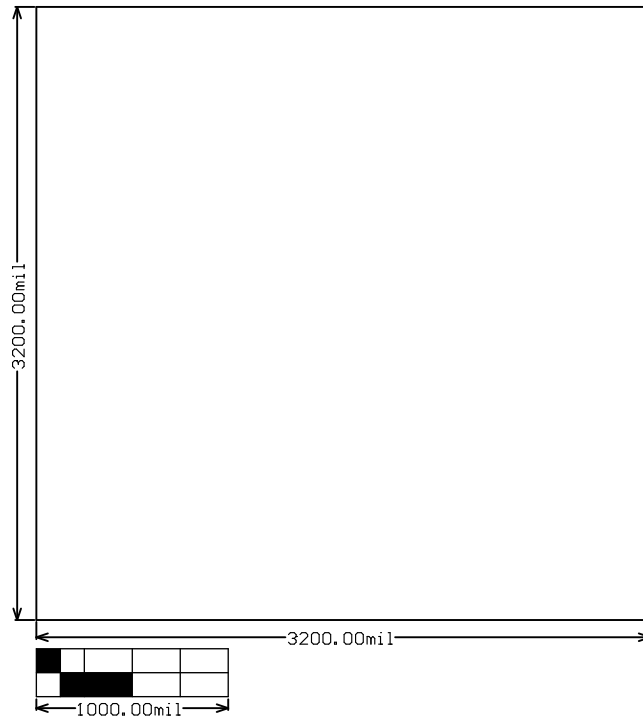


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20818		
PLOT NAME = Bottom Overlay	GENERATED : 3/29/2017 1:09:07 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
■	101	10.00mil (0.254mm)	PTH	Round
▽	5	14.00mil (0.356mm)	PTH	Round
✕	4	41.34mil (1.056mm)	PTH	Round
✕	8	45.28mil (1.150mm)	PTH	Round
■	17	63.00mil (1.600mm)	PTH	Round
✕	4	125.98mil (3.200mm)	PTH	Round
○	9	214.57mil (5.450mm)	PTH	Round
148 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20818		
PLOT NAME = Drill Drawing	GENERATED : 3/29/2017	1:09:08 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20818		
PLOT NAME = Board Dimensions	GENERATED : 3/29/2017 1:09:10 PM	TEXAS INSTRUMENTS	

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